METLOK®
Bonding & Sealing Solutions

EPOXY ADHESIVES

- 1K Epoxy
  - Bonding
  - Potting
  - Hemming Sealants
- 2K Epoxy
  - Bonding
  - Potting

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A must for Industrialists, Engineers, Architects, Developers, Professionals & Consultants.

My-T-BOND®
EPOXY Adhesives

1K Epoxy Bonding Adhesives

Single component epoxies are used for high strength and high impact bonding of magnets in the assembly of starters and alternators. These can be effectively used for the bonding magnet to magnet or metals.

PRODUCTS

	My-T-BOND® 2619 (Low Viscosity)	My-T-BOND® 2605 (Medium Viscosity)	My-T-BOND® 2689 (High Viscosity)
Description	It is a heat curable one component high viscosity, high strength industrial grade epoxy adhesive. It has excellent adhesion to wide range of substrates and withstands heavy impact load.	It is a heat curable one component medium viscosity epoxy adhesive. It develops tough and strong bonds which provide excellent impact strength, excellent mechanical and electric resistance. It has excellent resistant to a wide range of chemicals and solvents.	It is high strength high viscosity adhesive developed for structural applications. It is one component heat curable industrial grade epoxy adhesive. It develops to a tough and strong bond after curing and has good peel strength.
Appearance	Off-White	Grey	Black
Specific Gravity (25±2°C) ASTM D1875	1.17	1.1	1.25
Viscosity, Brookfield (25±2°C) ASTM D1084 (cP)	150000 - 200000	500000 - 600000	2000000 - 4000000
Cure Schedule	30min @ 150°C	60min @ 150°C	25min @ 175°C
Cure	Heat	Heat	Heat
Hardness Shore D (25±2°C) ASTM D2240	80	70-75	70 - 75
Lap Shear Strength ASTM D1002 (N/mm^2)	20 - 30	≥ 20	≥ 45
Tensile Strength ASTM D897 (N/mm^2)	20 - 25	≥ 18	40
Service Temperature (°C)	-40 to 150	-50 to 200	-50 to 150
Shelf Life (Months @ 5°C)	3	3	3
Pack Size (kg)	1 & 5	1 & 5	1 & 5

1K Epoxy Potting Adhesives

Potting is a process of filling a complete electronic assembly with a solutions for resistance to shock and vibration, and for exclusion of moisture and corrosive agents.

METLOK brings you range of potting solutions to meet your design.

PRODUCTS

	My-T-BOND® 2604 (Low Viscosity)	My-T-BOND® 2640 (Medium Viscosity)	My-T-BOND® 2620 (High Viscosity)
Description	It is a heat curable one component low viscosity, industrial grade epoxy adhesive. It has excellent adhesion to wide range of substrate ideally suitable for relay potting applications.	It is a low temperature heat curable, one component industrial grade epoxy adhesive ideally suitable for potting, sealing & encapsulation good for syringe bonding	It is a heat curable one component high viscosity, industrial grade epoxy adhesive. This one component-no mix formulation develops tough and strong bond which provide excellent mechanical strength and electric resistance and acts as an excellent electrical insulator.
Appearance	Black	White	Black
Specific Gravity (25±2°C) ASTM D1875	1.14	1.29	1.20
Viscosity, Brookfield (25±2°C) ASTM D1084 (cP)	4500 - 7500	40000 - 45000	90000 - 140000
Cure Schedule (Mins)	25 @ 100°C	30 @ 120°C	90 @ 120°C
Cure	Heat	Heat	Heat
Hardness Shore D (25±2°C) ASTM D2240	86 - 88	65 ± 3	85 - 90
Lap Shear Strength ASTM D1002 (N/mm^2)	10 - 15	≥ 20	18 - 25
Tensile Strength ASTM D897 (N/mm^2)	10 - 15	≥ 20	10 - 15
Service Temperature (°C)	-50 to 200	-50 to 200	-40 to 200
Shelf Life (Months @ 5°C)	3	3	3
Pack Size (kg)	1 & 5	1 & 5	1 & 5

My-T-BOND® EPOXY Adhesives

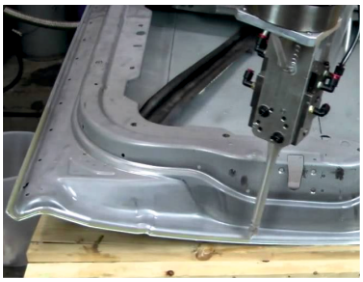
1K Hemming Sealants

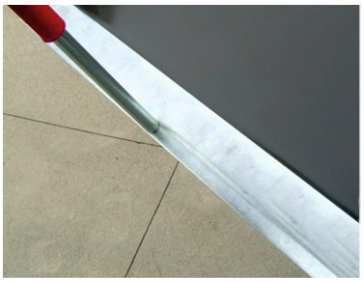
Hemming is a technology used in the automotive industry to join inner and outer closure panels together (hoods, doors, tailgates, etc.). It is the process of bending / folding the flange of the outer panel over the inner one.

Hemming adhesives are based on single component epoxy technology extensively used with hemming process in body shops of all automotive industries. It is solvent free one component heat curable hemming adhesives with excellent ageing and corrosion resistance with good wash-off resistance.

PRODUCTS

		My-T-BOND® 2699 LT (Low Temperature)	My-T-BOND® 2699 LV (Low Viscosity)
Description		It is a solvent free, one part, heat-cure, reactive adhesive with a low curing temperature of 120°C.	It is a solvent free, low viscosity version of hemming adhesive which has curing temperature of 120°C.
Appearance		BLACK	BLACK
Viscosity (25±2°C)		Thixotropic Paste	Thixotropic Paste
Specific Gravity (25±2°C)		1.36	1.36
Cure		Heat	Heat
Cure Schedule		30 Mins @ 120°C	60 Mins @ 150°C
Lap Shear Strength ASTM D1002	(N/mm^2)	15 - 20	25 - 30
Tensile Strength ASTM D897	(N/mm^2)	20 - 25	15 - 20
Hardness - Shore D (25±2°C) ASTM D2240		88	85
Shelf Life @ 5°C	(Months)	2-3	2-3
Pack Size	(g)	420	420



My-T-BOND® 2699 GB-10

(Glass Beads 10%)

My-T-BOND® 2699 GB-30

(Glass Beads 30%)

My-T-BOND® 2699 GB-50

(Glass Beads 50%)

These are solvent free, one part, heat-cure (150°C), hemming adhesives, available with Glass Bead variation of 10%, 30% and 50%. These are based on single component epoxy system which is applied in body shop and cures in oven. The product exhibits excellent bond and impact strength.

My-T-Bond 2699 Hemming Sealant has excellent ageing and corrosion resistance along with good wash-off resistance.

BLACK	BLACK	BLACK
Thixotropic Paste	Thixotropic Paste	Thixotropic Paste
1.64	1.61	1.59
Heat	Heat	Heat
60 Mins @ 150°C	60 Mins @ 150°C	60 Mins @ 150°C
23 - 28	20 - 25	20 - 25
28 - 33	28 - 33	20 - 25
90	85	85
2-3	2-3	2-3
420	420	420

My-T-BOND®
EPOXY Adhesives

2K Epoxy Bonding Adhesives

Two component epoxy adhesives provide high structural strength. They are suitable for bonding metals, ceramics, SMC and some plastics. These are also used for potting in electrical components, casting of switch gear component and insulators. Curing occurs upon mixing of the two components (resin and hardener). Fixture time is from 5-10 minutes to several hours. Applying heat accelerates the cure speed.

PRODUCTS

	My-T-BOND® 2708 (High Toughness)	My-T-BOND® 2776 (Hydrocarbon Resistant)	My-T-BOND® 2710 (Fast Curing)
Description	It is a toughened, Industrial grade epoxy adhesive. Once mixed, the two-component epoxy cures at room temperature to form a tough, off-white, bondline which provides high impact and high shear strengths.	It is an industrial grade two component soft epoxy adhesive. The fully cured epoxy has excellent resistance to acid, alkali, alcohols and hydrocarbons	It is a clear, medium viscosity, room temperature curing 2K-Epoxy system. After curing it cures to a tough polymer and develops good bonding strength with various plastics and metals substrates. It has good petrol and diesel resistance.
Appearance	Part A - Pale Yellow Part B - Yellow **A+B = Off White**	Part A - Blue Part B - Blue **A+B = Blue**	Part A - Clear Part B - Clear **A+B = Clear**
Specific Gravity (25±2°C) ASTM D1875	1.1 & 1.1	1.17 & 1.14	1.19 & 1.04
Viscosity ASTM D1084 (cP)	(A) 60000 - 90000 (B) 7000 - 10000	(A) Viscous Paste (B) Viscous Paste	(A) 11000 - 13000 (B) 14000 - 16000
Mix Ratio by Weight (A&B)	2:1	1:1	2:1
Pot Life @ 25±2°C (min)	30	45	18 - 20
Hardness Shore D (25±2°C) ASTM D2240	80 ± 3	16 ± 3	80 ± 3
Lap Shear Strength ASTM D1002 (N/mm^2)	20 - 30	5 - 9	≥ 6
Tensile Strength ASTM D897 (N/mm^2)	NA	5 - 9	≥ 7
Service Temperature (°C)	-30 to 150	-50 to 150	-30 to 150
Shelf Life @ 25±2°C (Months)	6	12	6
Pack Size	50 ml & 400 ml	1Kg & 5 Kg	50 ml & 400 ml

2K Epoxy Potting Adhesives

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METLOK brings you range of potting solutions to meet your design.

PRODUCTS

	My-T-BOND® 2722 (Low Exotherm)	My-T-BOND® 2738 (Fast Curing)	My-T-BOND® 2760 (Soft Epoxy)
Description	It is a solvent free, low viscosity two component epoxy adhesive with moderate work life and slow cure at ambient temperature. It is ready to use system having low viscosity with low exotherm ideally suitable for all electronic potting of electric & electronic components.	It is a fast curing 2K-Epoxy room temperature curing, thixotropic adhesive; it bonds and repairs a wide variety of materials. It offer superior thermal shock resistance, mechanical, electrical and impact resistant properties. Used for industrial assemble for multipurpose applications.	It is a solvent less, two component epoxy adhesive. It is a specially formulated and processed to obtain void free potting and encapsulation. It is ready to use system having medium viscosity at processing temperature and becomes a viscous liquid which, after curing, takes the form of a soft and durable material.
Appearance	Part A - Black Part B - Amber **A+B = Black**	Part A - Black Part B - Slight Yellow **A+B = Black**	Part A - Black Part B - Yellow **A+B = Black**
Specific Gravity (25±2°C) ASTM D1875	1.06 & 1.06	1.2 & 1.3	1.3 & 0.98
Viscosity (Spindle #6 @10rpm) ASTM D1084 (cP)	(A) 11300 - 14500 (B) 2750 - 4000	(A) 13000 - 15000 (B) 10000 - 16000	(A) 4000 - 4500 (B) 800 - 1200
Mix Ratio by Weight (A&B)	4:1	1:0.8	4:1
Pot Life @ 25±2°C (min)	90	3	180
Total Cure @ 25±2°C (Hrs)	24	24	72
Hardness Shore D (25±2°C) ASTM D2240	70 - 80	75 ± 3	60
Service Temperature (°C)	-30 to 150	-30 to 150	-30 to 150
Shelf Life @ 25±2°C (Months)	12	9	12
Pack Size	1 Kg & 5 Kg	50 ml & 400 ml	1 Kg & 5 Kg

METLOK®
Bonding & Sealing Solutions

METLOK PRIVATE LIMITED
METLOK PRECOAT SERVICES PRIVATE LIMITED

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